



Material Content Data Sheet



Sales Product Name		IPB110N20N3LF		Issued		24. January 2018		
MA#		MA001616172						
Package		PG-TO263-3-2		Weight*		1559.64 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	18.005	1.15	1.15	11544	11544
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		195	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59	
	non noble metal	copper	7440-50-8	304.026	19.49	19.52	194933	195187
wire	noble metal	gold	7440-57-5	0.066	0.00		42	
	non noble metal	aluminium	7429-90-5	10.509	0.67	0.67	6738	6780
encapsulation	organic material	carbon black	1333-86-4	9.992	0.64		6406	
	plastics	epoxy resin	-	109.909	7.05		70471	
	inorganic material	silicondioxide	60676-86-0	546.215	35.02	42.71	350218	427095
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6192	6192
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	146
glue	plastics	Polyimide	26023-21-2	1.118	0.07	0.07	717	717
solder	non noble metal	lead	7439-92-1	1.093	0.07		701	
	noble metal	silver	7440-22-4	0.029	0.00		18	
	non noble metal	tin	7440-31-5	0.023	0.00	0.07	15	734
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		352	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	35.13	35.18	351147	351605
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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